

**ATTACHMENT FOR SPECIFICATION AMENDMENTS**

Attorney Docket No. 9319S-000208

The following is a marked up version of each replacement paragraph and/or section of the specification in which underlines indicates insertions and brackets indicate deletions.

**[0024]** The base member 17 may preferably be formed from a material that has a small difference in the thermal expansion coefficient with respect to the first and second chips 12 and 13. For example, the base material 17 may be formed from a metal such as an [42] alloy.

**[0025]** The base member 17 may be in a frame shape that surrounds the first chip 12, or a column-like member that is disposed at a location where it can support the second chip 13. In order to securely support the second chip 13 [15], an area of the base member 17 to be located may preferably be generally the same as that of the first chip 12 or greater.

**[0029]** Next, the base member 17 is disposed outside the first chip 12. The base member 17 is affixed to the interposer substrate 11 by an adhesive such as thermosetting resin. Then, the second chip 13 that is larger than the first chip 12 is mounted on the first chip 12. In this case, the second chip 13 is affixed on the first chip 12 by an adhesive or the like. In this instance, portions of the second chip 13 [15] extending outside the first chip 12 are supported by the base member 17.

[0035] A filler layer 27 that is composed of a thermosetting resin or the like is provided as an undercoat layer between the first chip 22 and the second chip 23 [13]. In other words, the filler layer 27 is disposed at a location where it supports a portion of the second chip 23 that extends beyond the first chip 22.

**ATTACHMENT FOR CLAIM AMENDMENTS**

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The following is a marked up version of each amended claim in which underlines indicates insertions and brackets indicate deletions.

1. (Amended) A semiconductor device [characterized in] comprising:
  - a first semiconductor chip mounted on a substrate;
  - a second semiconductor chip mounted on the first semiconductor chip, the second semiconductor chip being larger than the first semiconductor chip;
  - a base member [that is] disposed between the second semiconductor chip and the substrate; and
  - a connection member disposed below the substrate,wherein the second semiconductor chip is supported by the base member.
  
2. (Amended) A semiconductor device [characterized in] comprising:
  - a first semiconductor chip mounted on a substrate;
  - a second semiconductor chip mounted on the first semiconductor chip, the second semiconductor chip being larger than the first semiconductor chip;
  - a filler layer [that is] provided between the second semiconductor chip and the substrate; and
  - a connection member disposed below the substrate,wherein the second semiconductor chip is supported by the filler layer.

3. (Amended) A method for manufacturing a semiconductor device, the method [characterized in] comprising the steps of:

mounting a first semiconductor chip on a substrate;

mounting a base member outside the first semiconductor chip on the substrate;

and

mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip, in a manner that the second semiconductor chip is supported by the base member.

4. (Amended) A method for manufacturing a semiconductor device, the method [characterized in] comprising the steps of:

mounting a first semiconductor chip on a substrate,

mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip; and

providing a filler layer in a manner to support the second semiconductor chip.